

REV.	DESCRIPTION	NAME	DATE
A	NEWS ISSUE	ERIC	2022/10/20

NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 - 2.CONTACTS: COPPER ALLOY
 - 3.MID PLATE: STAINLESS STEEL
 - 4.INSIDE SHELL: STAINLESS STEEL
 - 5.OUTSIDE SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 - (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - GOLD FLASH PLATING ON SOLDER AREA
 - 2-2.INSIDE SHELL OR OUTSIDE SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
- 3.MECHANICAL PERFORMANCE,
 - 3-1.INSERTION FORCE: 0.5~2.0kgf.
 - 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3.DURABILITY: 10000 CYCLES.
- 4.ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 5A
 - VOLTAGE RATING: 20V
 - 4-2.INSULATION RESISTANCE: 100MΩ MIN
 - 4-3.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
 - 4-4.LOW CONTACT RESISTANCE: INITIAL 40MΩ
 - AFTER 50MΩ
5. ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -30°C~+80°C.
- 6.IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

5	OUTER SHELL	SUS304 T=0.25MM	NI 40u"MIN	1PCS
4	INNER SHELL	SUS304 T=0.30MM	NI 40u"MIN	1PCS
3	SHIELDING PLATE	SUS301 T=0.15MM	N/A	1PCS
2	CONTACT	C2680 T=0.15MM	Mating area 1u"Au Solder Tails: G/F Underplate: 80u"Min Ni overall	2SET
1	INSERT MOLDING	LCP UL94V-0	BLACK	1PCS
NO.	DESCRIPTION	MATERIAL	REMARKS	

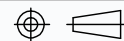
TOLERANCE UNSPECIFIED

.0	±0.35
.00	±0.25
.000	±0.15
X.°	±1.00°

ASSEMBLY DRAWING

CMTDDZ 东莞市田都科技有限公司
Dongguan TianDu Technology Co. Ltd.

TITLE: USB TYPE C 16PIN,
板上垫高1.90mm(CH=3.5)

DRAWN	ERIC	DATE	2022/10/20	SIZE:A4	UNIT:mm.	PART.NO:	T11-16BS04A-CH3.45		
CHECKED	JEFF	DATE	2022/10/20	SCALE:	1:1	PROJECTION		REV.:	A
APPROVED	COCO	DATE	2022/10/20	DWG	PATH	CMTDDZ-T11-16BS04A-CH3.45	PATH	1/3	

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7.P/N: T11-16BS04A-CH3.45-Y-001R

16:16 PIN

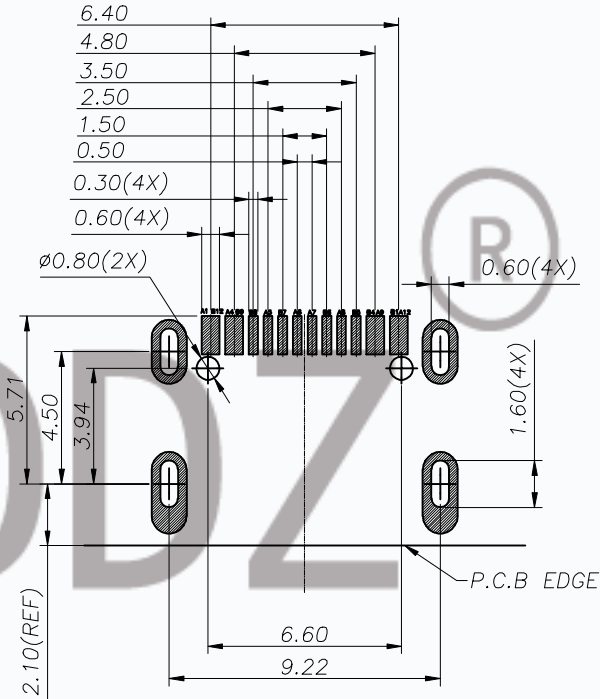
B:Black
N:NATURE

- 1: GOLD FLASH PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER AREA
- 3: 3u" GOLD PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER AREA
- 5: 3u" GOLD PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER AREA

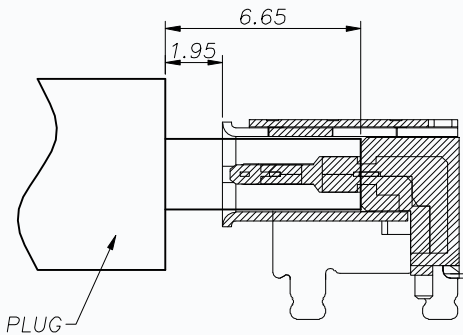
USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME
A1	GND
A4	VBUS
A5	CC1
A6	Dp1
A7	Dn1
A8	SBU1
A9	VBUS
A12	GND

PIN NUMBER	SIGNAL NAME
B12	GND
B9	VBUS
B8	SBU2
B7	Dn2
B6	Dp2
B5	CC2
B4	VBUS
B1	GND



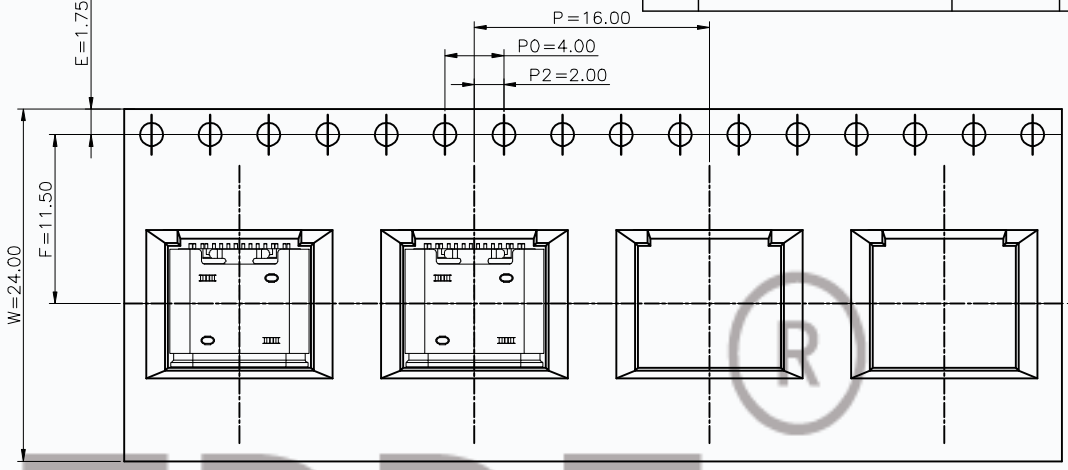
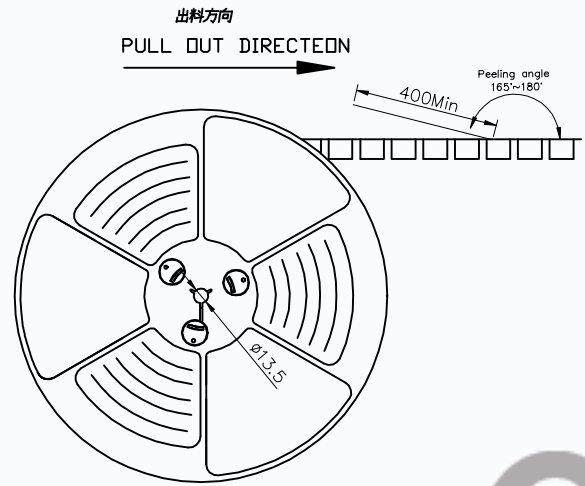
RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)
TOLERANCE FOR PCB LAYOUT IS ± 0.05



AFTER MATING
SCALE 1:1

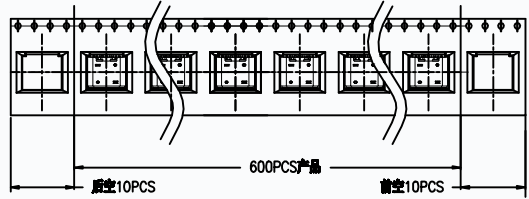
TOLERANCE UNSPECIFIED		CMTDDZ 东莞市田都科技有限公司 Dongguan TianDu Technology Co. Ltd.		
.0	±0.35			
.00	±0.25			
.000	±0.15			
X."	±1.00"			
ASSEMBLY DRAWING		TITLE: USB TYPE C 16PIN, 板上垫高1.90mm(CH=3.50)		
DRAWN	ERIC	SIZE:A4	UNIT:mm.	PART.NO: T11-16BS04A-CH3.45
DATE	2022/10/20	SCALE: 1:1	PROJECTION	REV.: A
CHECKED	JEFF	DWG	PATH	CMTDDZ-T11-16BS04A-CH3.45
DATE	2022/10/20			PATH 2/3
APPROVED	COCO			
DATE	2022/10/20			

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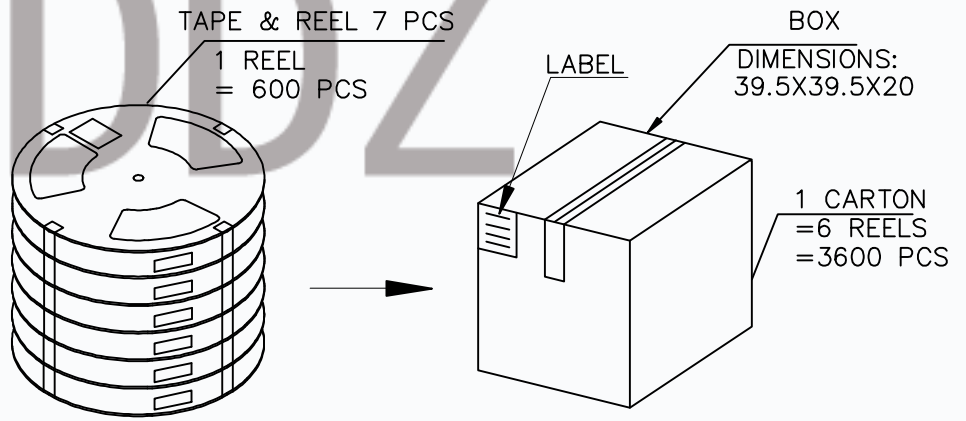


NOTES

1. 帶子引導長度
LEAD TAPE LENGTH



2. 上帶 剝離力為: 0.1~1.3N(10.2gf~130gf)
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N(10.2gf~130gf)
出貨 運輸過程中一定注意:
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT:
卷帶在運輸過程中不能散開
PEELING OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION



TOLERANCE UNSPECIFIED		CMTDDZ 东莞市田都科技有限公司 Dongguan TianDu Technology Co. Ltd.	
.0	±0.35	TITLE: USB TYPE C 16PIN, 板上墊高1.90mm(CH=3.50)	
.00	±0.25	SIZE: A4	UNIT: mm. PART. NO: T11-16BS04A-CH3.45
.000	±0.15	CHECKED DATE: JEFF 2022/10/20	SCALE: 1:1 PROJECTION REV.: A
X *	±1.00*	APPROVED DATE: COCO 2022/10/20	DWG PATH: CMTDDZ-T11-16BS04A-CH3.45 PATH 3/3

包裝明細表 (The detail of the packing) Carton						
產品料號 (Product No.)	包裝容量 (Packing Capacity)			重量 Weight (Kg)		
	pcs/box	boxs/Carton	Pcs/Box	N.W./Pcs	N.W./Box	G.W./Box
T11-16BS04A-CH3.45	600	6	3600	—	—	—